

# EUROPEAN PATENT OFFICE

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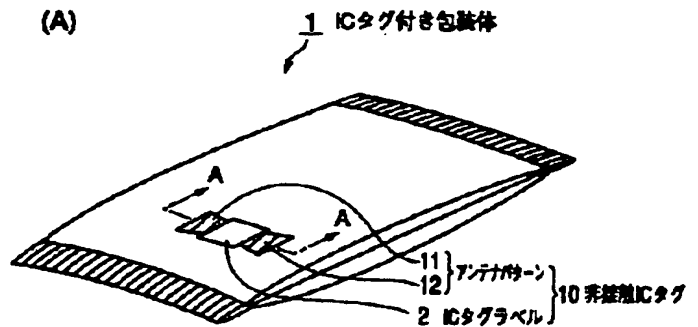
APPLICANT : DAINIPPON PRINTING CO LTD;

INVENTOR : SHIINA TOKUYUKI;

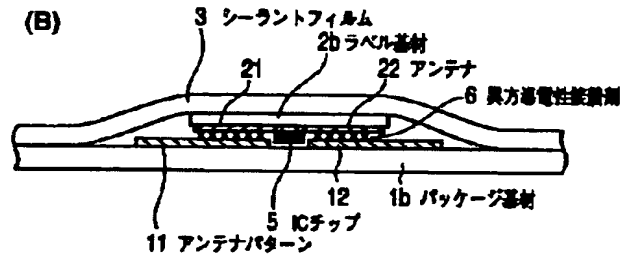
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TITLE : PACKAGE WITH IC TAG AND  
MANUFACTURING METHOD FOR THE  
PACKAGE WITH IC TAG

(A)



(B)



ABSTRACT : PROBLEM TO BE SOLVED: To provide a package with an IC tag from which the contactless IC tag never falls in its distribution stage and its manufacturing method.

SOLUTION: The package 1 with the IC tag is mounted with the IC tag having a contactless communication function and an antenna made of conductive ink is printed in arbitrary pattern on part of at least a base material film or sheet; and an IC tag label 2 is mounted on the antenna printed surface and a sealant film is laminated on the IC tag label surface to form a laminated body. The manufacturing method for the package with the IC tag is characterized in that after the IC tag label is mounted on the base material film or sheet, the sealant film is laminated.

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